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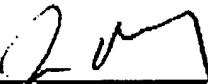
Remarks

The telephonic interview of today's date is gratefully acknowledged. It was agreed that the materials now recited in Claim 1 (lower Rh/upper Ta) would define patentable subject matter. It was also agreed that lower Ta/upper Cu and lower Au/upper Cu, two of the four combinations in amended Claim 13, were not present in the new Kobayashi '587 reference. The third combination in Claim 13 is the aforementioned Rh/Ta. The fourth combination in Claim 13 (Rh/AI) was not specifically discussed to the best of the undersigned's recollection but it appears that none of the applied references teach or suggest this combination.

Apropos the Ta/Cu and Au/Cu combinations of Claims 13, 23, and 24, Applicant would like to point out that while the previously cited Hasegawa et al. teaches a bottom lead layer made of a specific alloy of gold (Au alloyed with either Pb, Cr, or Cu or Au alloyed with Cr, Rh, Ru, Ta, or W, paragraph 35) and a top lead layer made of Au, Cu, or Ag, the focus on the materials is ductility (paragraph 34), not polish resistance, and that it is not taught that the specific alloys of the bottom layer have a lower removal rate than those of the top layer as otherwise recited in Claim 13.

The examiner is cordially invited to telephone the undersigned for any reason that would advance the instant application to allowance.

Respectfully submitted,


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